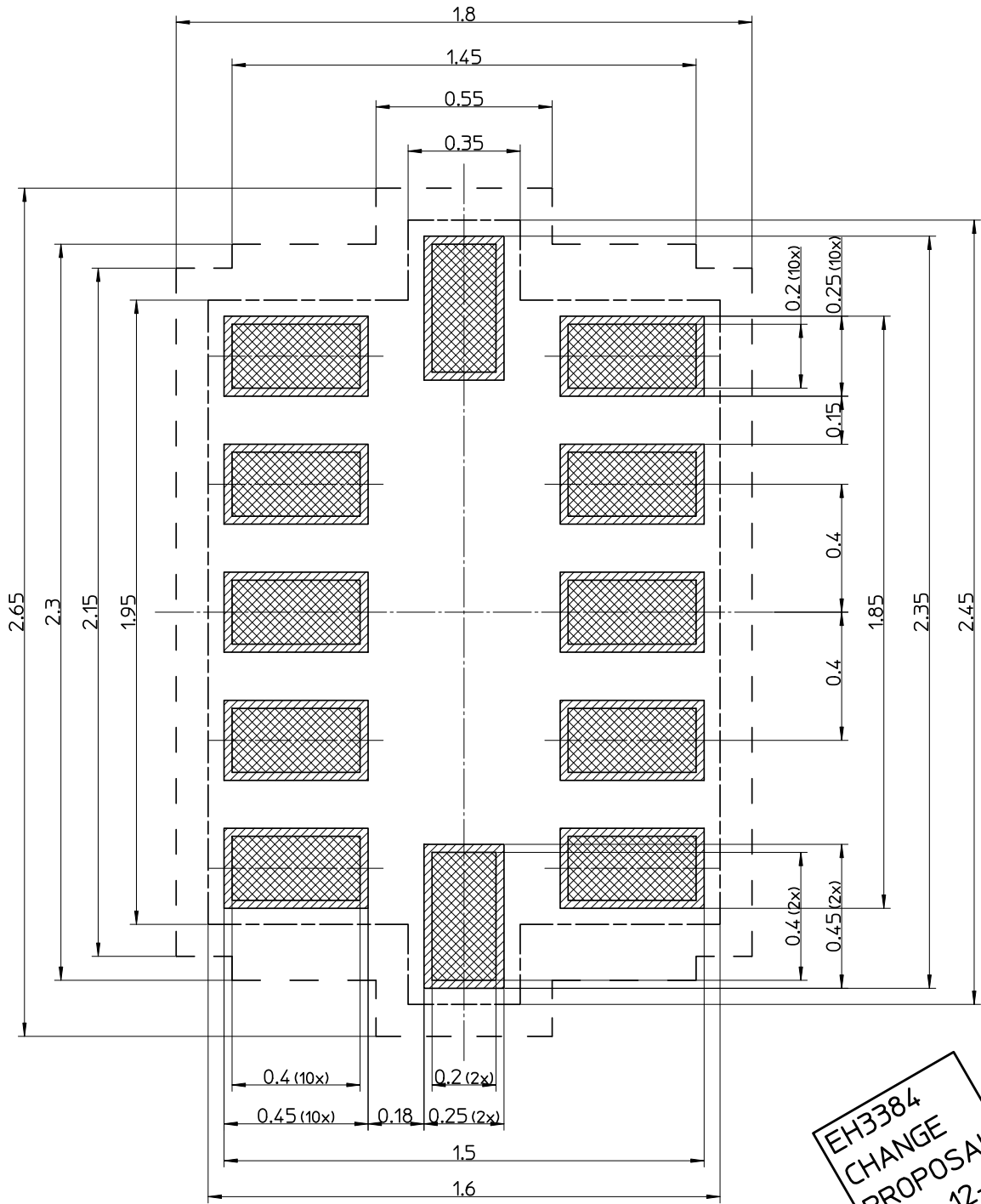




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EH3384
CHANGE
PROPOSAL
2014-12-17

REFLOW SOLDERING

-
 Occupied Area
 Solder Resist
-
 Solder Lands
 Solder Paste

Proj. 	Scale 60:1	Unit mm	Tol. unless otherw. stated ±	 Ra in µm	ISO 1302	 A	ISO 1101	 A	Typ u a.
<div style="border: 1px solid black; width: 100px; height: 30px; display: inline-block;"></div> SOLDER LAYOUT SOT1408-1					<div style="border: 1px solid black; width: 100px; height: 30px; display: inline-block;"></div> EH3384				
Name: SHI Yuning		DWG No.: EH3384		1		110 - 1		010 - - - A 4	
PV	Check :	Dat.: 2014-12-17		(c) NXP Semiconductors / TCC					